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Contents

HYBRID INTEGRATED OPTICAL LINK MODULES

- 11692 04 **Short reach, high temperature operation and high reliability silicon photonic micro-transceivers for embedded and co-packaged system integration (Invited Paper)** [11692-1]
- 11692 05 **Co-packaged optics for HPC and data center networks (Invited Paper)** [11692-2]

OPTICAL INTERCONNECT DEVICES

- 11692 06 **Monolithically integrable optical single sideband transmitter for low-cost, high-density optical interconnects (Invited Paper)** [11692-3]
- 11692 07 **Silicon photonic switches (Invited Paper)** [11692-4]
- 11692 0C **The role of VCSELs in 3D sensing and LiDAR** [11692-9]
- 11692 0D **NRZ, DB, and DMT performance for short-reach VCSEL-based optical interconnects** [11692-10]

PICS FOR OPTICAL INTERCONNECTS

- 11692 0H **From integrated photonic transceivers to all-optical logic (Invited Paper)** [11692-14]
- 11692 0I **Ultra-long grating emitters for optical phased array leveraging subwavelength structures (Invited Paper)** [11692-15]

NOVEL OPTICAL WAVEGUIDE AND INTEGRATED INTERCONNECT TECHNOLOGIES

- 11692 0K **Thermally stable single-mode glass waveguides with fiber connectors for co-packaged optics (Invited Paper)** [11692-17]
- 11692 0M **3D nanoprinting of mode-field conversion tapers for low-loss optical interfacing of single-mode fibers and photonic integrated circuits (Invited Paper)** [11692-19]
- 11692 0N **Interconnection challenges on integrated terahertz photonic systems (Invited Paper)** [11692-20]

HYBRID DEVICE INTEGRATION APPROACHES FOR PIC

- 11692 OR **Integrated high-speed quantum random number generators for mobile, IOT, and edge applications (Invited Paper)** [11692-24]
- 11692 OT **A particle swarm optimization approach for designing III-V/Si vertical couplers** [11692-26]

OPTICAL INTERCONNECT SYSTEMS

- 11692 OW **A silicon photonic evanescent-field sensor architecture using a fixed-wavelength laser (Invited Paper)** [11692-29]
- 11692 OX **An overview of key optical communications technologies under development at the NASA Glenn Research Center (Invited Paper)** [11692-30]
- 11692 OZ **Maximizing the impact of emerging photonic switches at the system level** [11692-32]
- 11692 IO **Resilient architectures for free space optical wireless interconnection systems** [11692-33]

FIBER OPTICS AND MICRO-OPTIC ASSEMBLY

- 11692 I3 **Probabilistic deep neural network based signal processing for Brillouin gain and phase spectrums of vector BOTDA system** [11692-36]
- 11692 I4 **Next generation multi-fiber ferrule using 165 micron pitch optical fiber** [11692-37]
- 11692 I8 **Extremely low-loss and bendable tapered multi-core fiber with double core structure for compact assembly of silicon photonics multi-port devices** [11692-41]